

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE

HN1K02FU

HIGH SPEED SWITCHING APPLICATIONS

Unit in mm

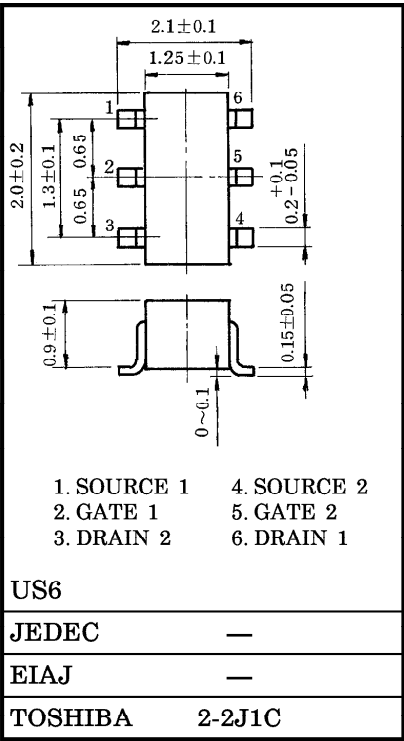
ANALOG SWITCH APPLICATIONS

- 2.5 Volts Gate Drive.
- Low Threshold Voltage : $V_{th}=0.5\sim1.5V$
- High Speed
- Enhancement-Mode
- Small Package

MAXIMUM RATINGS (Ta = 25°C) (Q1, Q2 COMMON)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GSS}	10	V
DC Drain Current	I_D	50	mA
Drain Power Dissipation	P_D^*	200	mW
Channel Temperature	T_{ch}	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

* Total Rating



Weight : 6.8mg

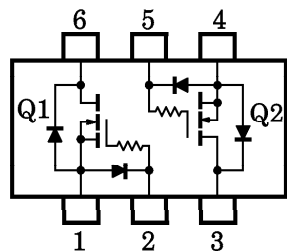
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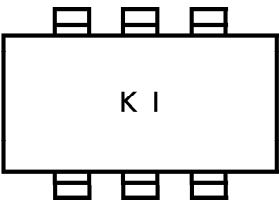
ELECTRICAL CHARACTERISTICS (Ta = 25°C) (Q1, Q2 COMMON)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I_{GSS}	$V_{GS}=10V, V_{DS}=0$	—	—	1	μA
Drain-Source Breakdown Voltage		$V_{(BR) DSS}$	$I_D=100\mu A, V_{GS}=0$	20	—	—	V
Drain Cut-off Current		I_{DSS}	$V_{DS}=20V, V_{GS}=0$	—	—	1	μA
Gate Threshold Voltage		V_{th}	$V_{DS}=3V, I_D=0.1mA$	0.5	—	1.5	V
Forward Transfer Admittance		$ Y_{fs} $	$V_{DS}=3V, I_D=10mA$	20	—	—	mS
Drain-Source ON Resistance		$R_{DS(ON)}$	$I_D=10mA, V_{GS}=2.5V$	—	20	40	Ω
Input Capacitance		C_{iss}	$V_{DS}=3V, V_{GS}=0, f=1MHz$	—	5.5	—	pF
Reverse Transfer Capacitance		C_{rss}	$V_{DS}=3V, V_{GS}=0, f=1MHz$	—	1.6	—	pF
Output Capacitance		C_{oss}	$V_{DS}=3V, V_{GS}=0, f=1MHz$	—	6.5	—	pF
Switching Time	Turn-on Time	t_{on}	$V_{DD}=3V, I_D=10mA, V_{GS}=0\sim 2.5V$	—	0.14	—	μs
	Turn-off Time	t_{off}	$V_{DD}=3V, I_D=10mA, V_{GS}=0\sim 2.5V$	—	0.14	—	μs

EQUIVALENT CIRCUIT (TOP VIEW)

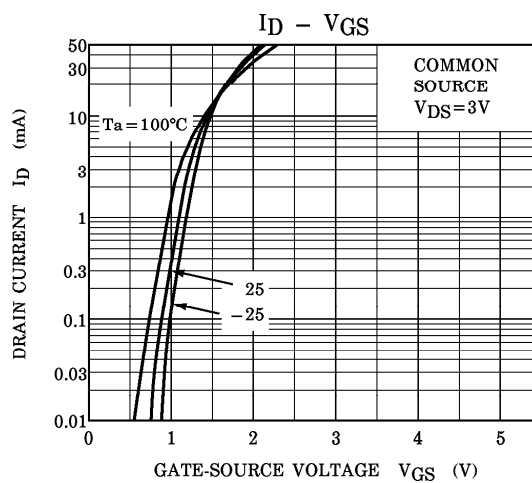
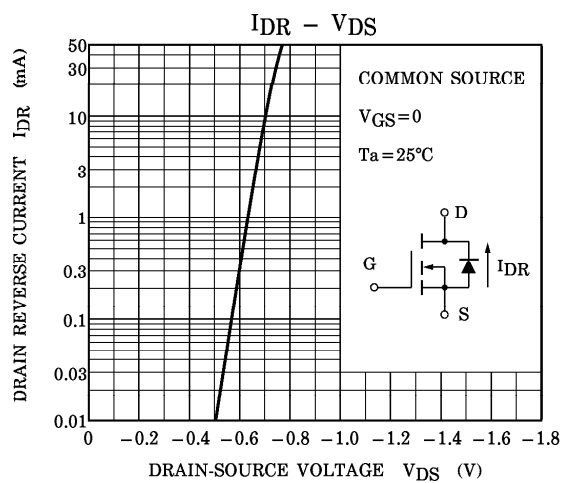
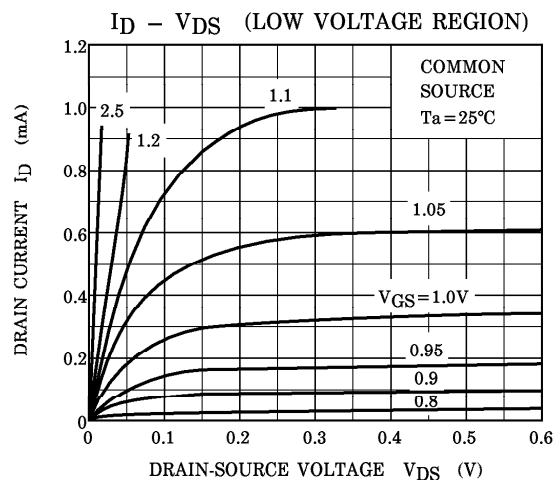
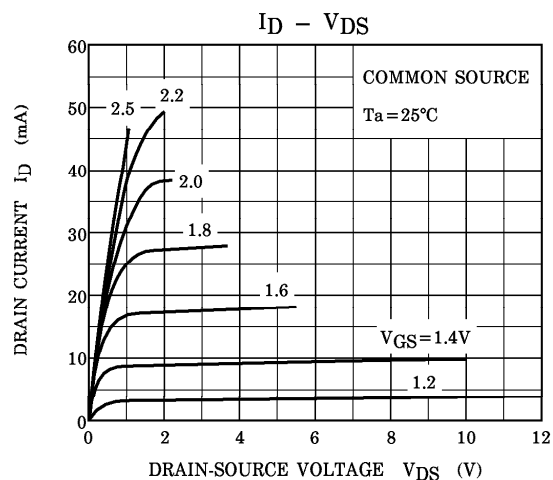
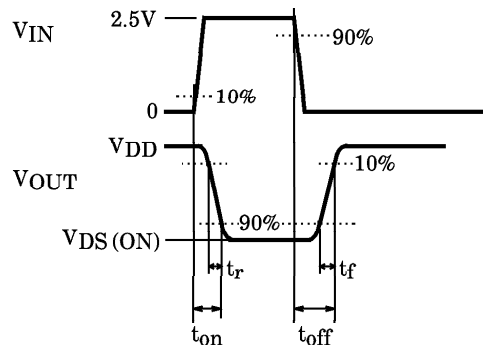
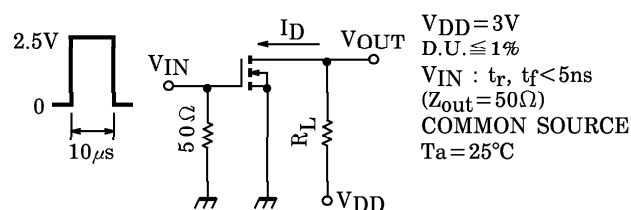


MARKING



(Q1, Q2 COMMON)

SWITCHING TIME TEST CIRCUIT



(Q1, Q2 COMMON)

